

ABSTRACT

The invention provides an organometallic complex, containing oxygen free organic ligands, for the deposition of a metal, preferably copper, silver or gold, and preferably by way of chemical vapor deposition. The organometallic complex having the formula



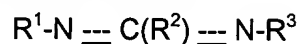
where M is a metal preferably selected from the group consisting of Cu, Ag and Au;
 D_o is selected from the group comprising ethers, phosphines, olefins, sulfides, pyridines, carbonyl, hydroxyl, cyclopentadiene, benzene derivatives, allyls, alkyls, amines, polyamines, aniline derivatives, cyclooctadiene and combinations thereof;

n is an integer having a value from 0 to 4;

k is an integer having a value from 1 to 4;

x is an integer having a value from 1 to 4; and

L is an amidinate ligand of the formula



where R^1 , R^2 and R^3 are selected from the group consisting of alkyls, allyls, aryls, heteroaryls, hydrogen, non-metals and metalloids; and where R^1 , R^2 and R^3 are different or the same.